

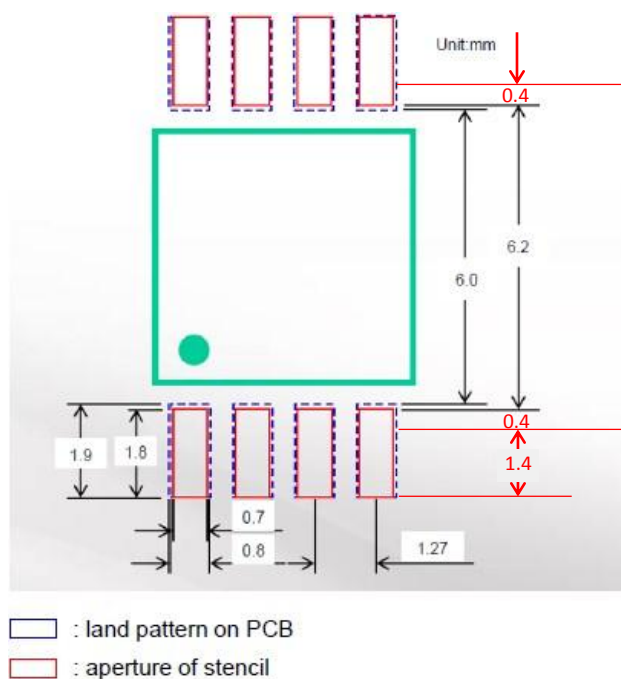
Introduction

This application note explains how the SOP8 208mil package (package code SS or S) is footprint compatible with the WSON8 8x6mm package (package code ZE or E) on a PCB layout.

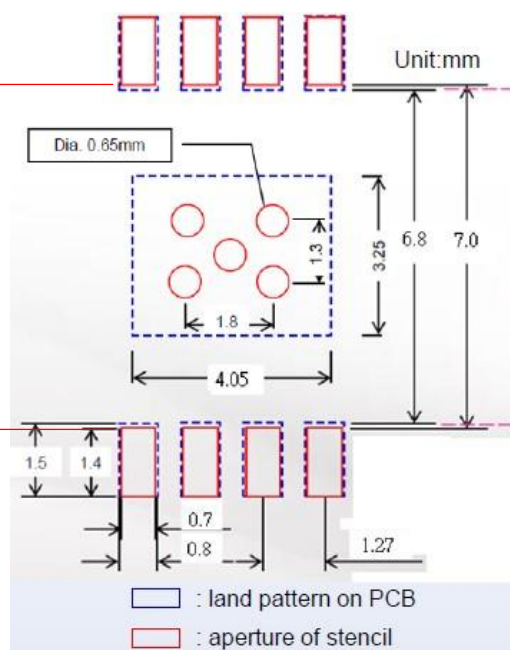
Package Land Pattern Comparison

Many Winbond flash products are available in both the SOP8 208mil package and the WSON8 8x6mm package. In cases where the system designer would like the flexibility to layout a board that can accept either package, only minor adjustments are required to accomplish such dual layout.

SOP8 208mil Land Pattern



WSON8 8x6mm Land Pattern



As illustrated in the above land patterns, the pad pitch is the same 1.27mm. The width of both packages is also the same 9.8mm (SOP8 = 6.2+1.8+1.8; WSON8 = 7.0+1.4+1.4). This means the WSON8 package will be able to fit on the SOP8 land pattern.

Note that the center pad of the WSON8 8x6mm package is for mechanical strength, to prevent die cracks and is not connected internally. It can be left floating.

Revision History

Version	Date	Page	Description
1.0	11/22/2023	NA	Original

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